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	Serial I	Mohammed Fathimulla and Thomas Keyser Man Park No.: 10/764,938 Date: January 26, 2004))) Examiner: Long Pham) Group Art Unit: 2814	
	For:		n-On-Insul		or RF Integrated)))	
					<u>TRANSMI</u>	TAL LETTER	
	P.O. Bo	x 145	r for Pate 0 \ 22313-				
	In regard to the above-identified patent application:						
	1. We are transmitting herewith the attached:						
		a) b) c)	PTO For	n 144	tter in Duplicate; 19; and References.		
	2.	With r	respect to	addi [,]	tional fees:		
				A.	No additional fee is re	quired.	
			\boxtimes	B.	Attached is a check in	the amount of \$ <u>180.00</u> .	
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01 FC:1806			180	.00 OP		spectfully Submitted, Donnell Boehnen Hulbert & Bergh	off LLP
			Date: Ar	<u>oril 9,</u>		isa M. Schoedel Reg. No. 53,564	<u>e</u>

McDonnell Boehnen Hulbert & Berghoff LLP 300 South Wacker Drive Chicago, Illinois 60606 Telephone: (312) 913-0001 Facsimile: (312) 913-0002

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Honeywell Ref. No. H0002270 DIV

Serial No.

MBHB Case No. 06-308-E

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INFORMATION DISCLOSURE STATEMENT BY APPLICANT

Applicant: Fathimulla et al.

Filing Date:

January 26, 2004

Group: 2814

U.S. PATENT DOCUMENTS

Examiner Initial	No.	Document Number	Date	Name	Class	Subclass	Filing Date

FOREIGN PATENT DOCUMENTS

Examiner Initial	No.	Document Number	Date	Country	Class	Subclass	<u>Translation</u> Yes No

OTHER DOCUMENTS - Including Author, Title, Date, Pertinent Pages, Etc.

Examiner Initial	No.	·
	1.	A.B Glaser et al., "Integrated Circuit Engineering," p. 265-267, 289 Addison-Wesley, 1977
	2.	U.S. Davidsohn and F. Lee., "Dielectric-Isolated Integrated-Circuit Substrate Processes." Proc. IEEE 57: 1532-1537 (September 1969).